

HLE-130-02-F-DV REPRESENTATION OF THE PROPERTY HLE-110-02-L-DV HLE-116-02-L-DV-K **HLE SERIES**

OTHER

OPTION

-BE

= Bottom Entry (Not available

with -TE)

= Alignment Pin (4 positions min.)

Metal or plastic at

Samtec discretion

(Not available with

-TE, -PE & -LC)

-LC

= Locking Clip

(2 positions min.)

(Not available with -A)

(Manual placement required)

= (6.50 mm) .256"

DIA Polyimide

Film Pick & Place Pad

(3 positions min.)

. Not available

with –TE or -PE tail option

.P = Metal Pick & Place Pad (3 positions min.)

-TR

= Tape & Reel

Packaging (29 positions

max.)

-FR

= Full Reel

Tape & Reel

Packaging

(Must order max.

quantities per reel.

Contact Samtec

for parts per reel)

(2.54 mm) .100"

COST-EFFECTIVE RELIABLE SOCKET

Mates With:

TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLÉ

Insulator Material:

Black Liquid Crystal Polymer Contact Material:

Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating (HLE/TSM):

4.1 A per pin (2 pins powered)
Voltage Rating:
400 VAC

Operating Temp Range:

-55 °C to +125 °C Insertion Depth: (1.78 mm) .070" to (3.43 mm) .135", pass-through, or (2.59 mm) .102" min

plus board thickness for bottom entry

RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-20) (0.15 mm) .006" max (21-50)*

(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

· Other platings

Some lengths, styles and options are non-standard, non-returnable.

